CW レーザーアニールによる歪み n 型 Ge の成長

Tensile Strained n-type Ge Grown by Continuous Wave Laser Annealing

物材機構¹,筑波大²,産総研³

⁰ラハマトハディサプトロ^{1,2}, 松村 亮¹, 前田 辰郎³, 深田 直樹^{1,2}

NIMS¹, Univ. of Tsukuba², AIST³

°Rahmat Hadi Saputro^{1,2}, Ryo Matsumura¹, Tatsuro Maeda³, Naoki Fukata^{1,2}

E-mail: SAPUTRO.RahmatHadi@nims.go.jp

[Introduction] Germanium (Ge) is one of the promising materials for optoelectronic device integration. It is widely known that Ge is an indirect-band semiconductor like Silicon (Si). However, by introducing tensile strain, the small difference (0.136 eV) between direct and indirect gaps can be reduced. Furthermore, it was mentioned that in 0.2-0.3% tensile strained Ge, n-type doping in the order of 10¹⁹ cm⁻³ could result in quasi directband light emission. [1] Recently, we have successfully crystallized amorphous Ge on quartz substrate by continuous wave laser annealing (CWLA), which also resulted in the introduction of 0.55-0.62% tensile strain. [2] In this study, we applied the similar technique for the Sb-doped ntype Ge film.

[Experimental Procedure] Poly-crystalline Ge films with ~ 10^{19} cm⁻³ of Sb concentration were deposited on quartz substrate by molecular beam deposition at 450°C growth temperature. Then, 300 nm of SiO₂ capping layer was deposited by sputtering at room temperature. The samples are inserted in the CWLA system [2] then annealed at laser scan speed (v_{scan}) of 800 m/min and laser power (E_{laser}) varied from 300 to 1000 mW.

seen on the annealed sample surface [Figs. 1(a), 1(b)] due to crystallization. Here, Raman spectra of the Sb-doped Ge samples shows Ge-Ge peak indicating the crystallization of the Ge films and it is largely shifted in high E_{laser} at about -3.6 cm⁻¹ [Fig. 1(c)]. This difference could be explained by the liquid phase recrystallization after Ge laver melted by the laser heat. Fig. 1(d) shows the change of peak shift from the as-grown to laser-annealed conditions for the Sb-doped and the undoped Ge. We consider that tensile strain is accumulated during cooling after solidification of Ge layer, due to thermal expansion, since its amount (~0.63% at 1000mW) agreed with the difference of thermal expansion coefficient between solidification temperature (938°C) and room temperature (-0.6%). [3] These results show the successful growth of tensile strained n-Ge films by the CWLA method. This finding will be useful for the growth of Ge-based films toward the development of Ge-based optoelectronics.

[1] J. Liu et al., Semicond. Sci. Technol. 27, (2012).
[2] R. Matsumura et al., ECS J. Solid State Sci. Technol. 9, 063002 (2020).

[3] M. E. Straumanis et al., *J. Appl. Phys.* 23, 330 (1952).





[Results & Discussion] Change of contrast were